

DATA SHEET

74F827

10-bit buffer/line driver, non-inverting
(3-State)

74F828

10-bit buffer/line driver, inverting
(3-State)

Product specification

1994 Dec 5

IC15 Data Handbook

Philips Semiconductors



PHILIPS

Buffers

74F827, 74F828

74F827 10-bit buffer/line driver, non-inverting (3-State)

74F828 10-bit buffer/line driver, inverting (3-State)

FEATURES

- High impedance NPN base inputs for reduced loading (20µA in High and Low states)
- I_{IL} is 20µA vs FAST family spec of 600µA and 1000µA for AMD 29827/29828 series
- Ideal where high speed, light bus loading and increased fan-in are required
- Controlled rise and fall times to minimize ground bounce
- Glitch free power-up in 3-State
- Flow through pinout architecture for microprocessor oriented applications
- Outputs sink 64mA
- 74F827 available in SSOP type II package

DESCRIPTION

The 74F827 and 74F828 10-Bit buffers provide high performance bus interface buffering for wide data/address paths or buses carrying parity. They have NOR Output Enables ($\overline{OE}0$, $\overline{OE}1$) for maximum control flexibility.

The 74F827 and 74F828 are functionally and pin compatible to AMD AM29827 and AM29828. The 74F828 is an inverting version of 74F827.

TYPE	TYPICAL PROPAGATION DELAY	TYPICAL SUPPLY CURRENT (TOTAL)
74F827	6.0ns	60mA
74F828	6.0ns	55mA

ORDERING INFORMATION

PACKAGES	COMMERCIAL RANGE $V_{CC} = 5V \pm 10\%$; $T_A = 0^\circ C$ to $+70^\circ C$	DRAWING NUMBER
24-Pin Plastic DIP (300 mil)	N74F827N, N74F828N	SOT222-1
24-Pin Plastic SOL	N74F827D, N74F828D	SOT137-1
24-Pin Plastic SSOP Type II	N74F827DB	SOT340-1

INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

PINS	DESCRIPTION	74F(U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
D0-D9	Data inputs	1.0/0.033	20µA/20µA
$\overline{OE}0$ - $\overline{OE}1$	Output enable inputs (active Low)	1.0/0.033	20µA/20µA
Q0-Q9	Data outputs (74F827)	1200/106.7	24mA/64mA
$\overline{Q}0$ - $\overline{Q}9$	Data outputs (74F828)	1200/106.7	24mA/64mA

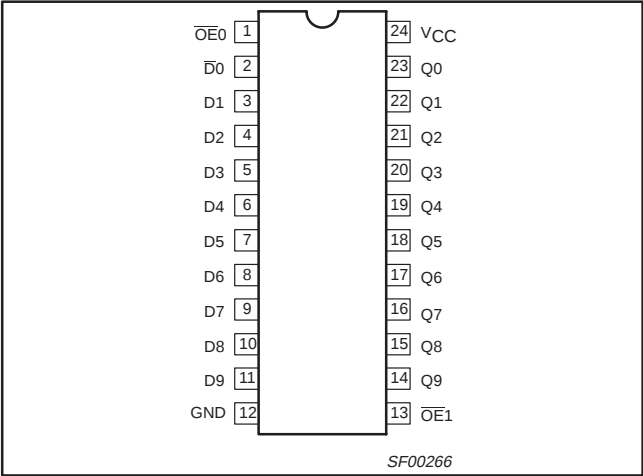
NOTES:

One (1.0) FAST Unit Load is defined as: 20µA in the High state and 0.6 mA in the Low state.

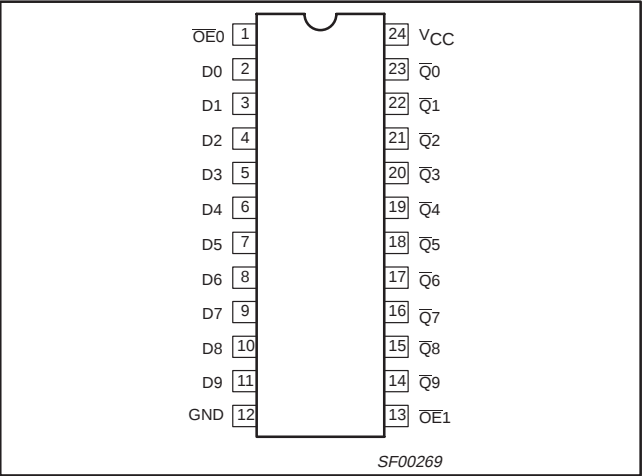
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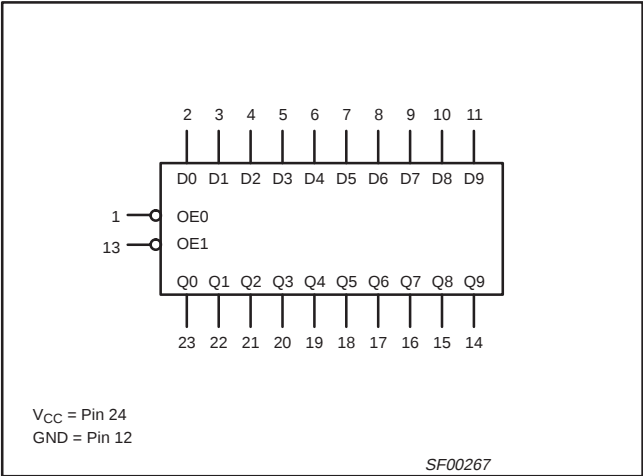
PIN CONFIGURATION - 74F827



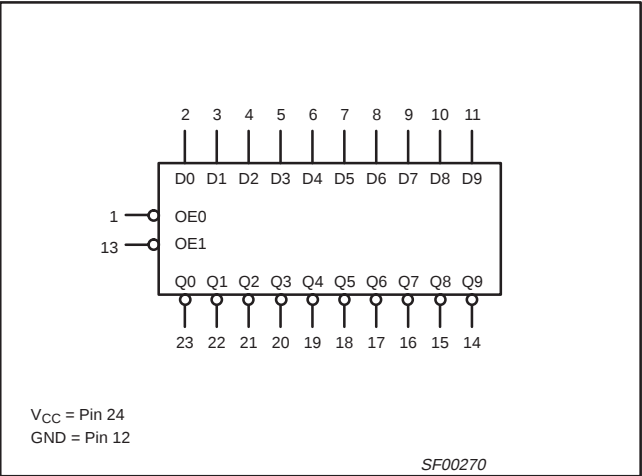
PIN CONFIGURATION - 74F828



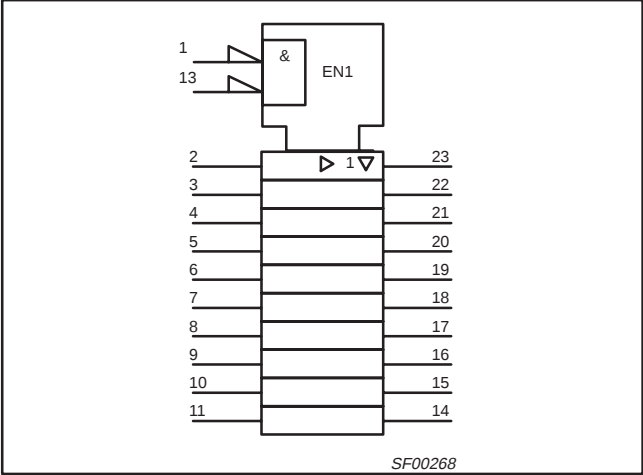
LOGIC SYMBOL - 74F827



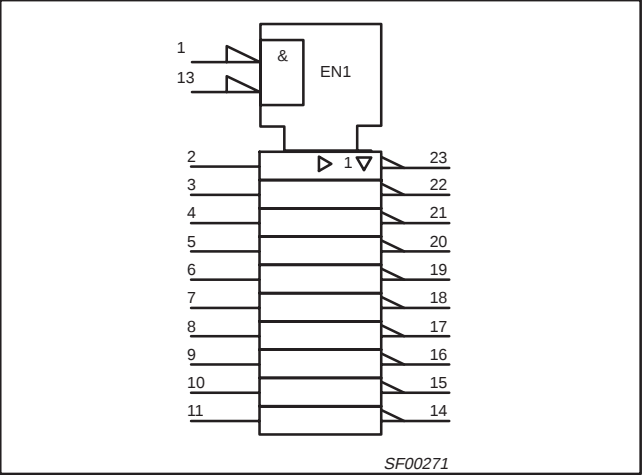
LOGIC SYMBOL - 74F828



LOGIC SYMBOL (IEEE/IEC) - 74F827



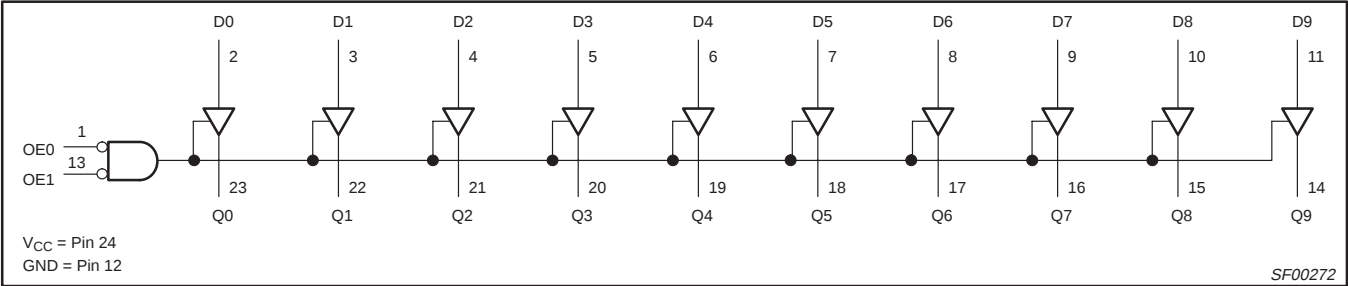
LOGIC SYMBOL (IEEE/IEC) - 74F828



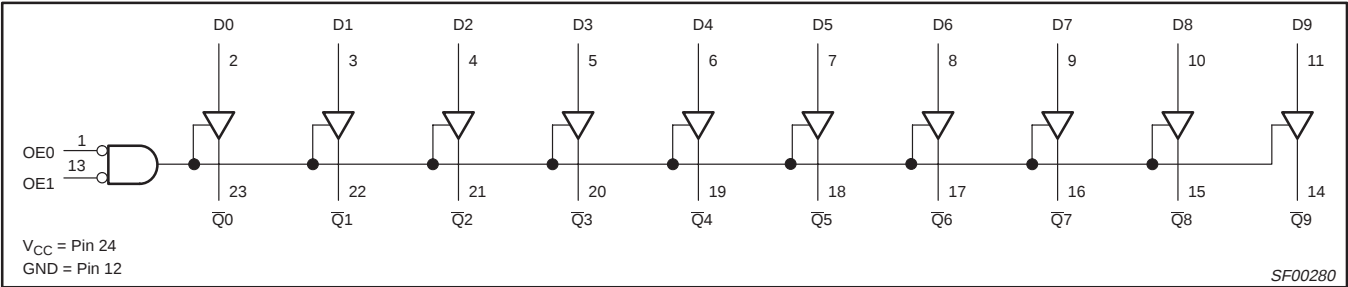
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LOGIC DIAGRAM 74F827



LOGIC DIAGRAM 74F828



FUNCTION TABLE

INPUTS		OUTPUTS		OPERATING MODE
		74F827	74F828	
$\overline{OE}n$	Dn	Qn	$\overline{Q}n$	
L	L	L	H	Transparent
L	H	H	L	Transparent
H	X	Z	Z	High impedance

H = High voltage level
L = Low voltage level
X = Don't care
Z = High impedance "off" state

ABSOLUTE MAXIMUM RATINGS

Operation beyond the limits set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free-air temperature range.

SYMBOL	PARAMETER	RATING	UNIT
V_{CC}	Supply voltage	−0.5 to +7.0	V
V_{IN}	Input voltage	−0.5 to +7.0	V
I_{IN}	Input current	−30 to +5	mA
V_{OUT}	Voltage applied to output in High output state	−0.5 to + V_{CC}	V
I_{OUT}	Current applied to output in Low output state	128	mA
T_A	Operating free-air temperature range	0 to + 70	°C
T_{stg}	Storage temperature range	−65 to + 150	°C

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RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIMITS			UNIT
		Min	Nom	Max	
V_{CC}	Supply voltage	4.5	5.0	5.5	V
V_{IH}	High-level input voltage	2.0			V
V_{IL}	Low-level input voltage			0.8	V
I_{IK}	Input clamp current			-18	mA
I_{OH}	High-level output current			-24	mA
I_{OL}	Low-level output current			64	mA
T_{amb}	Operating free-air temperature range	0		+70	°C

DC ELECTRICAL CHARACTERISTICS

Over recommended operating free-air temperature range unless otherwise noted.

SYMBOL	PARAMETER			TEST CONDITIONS ¹			LIMITS			UNIT
							MIN	TYP ²	MAX	
V _{OH}	High-level output voltage			V _{CC} = MIN, V _{IL} = MAX, V _{IH} = MIN	I _{OH} = −15mA	± 10%V _{CC}	2.4			V
						± 5%V _{CC}	2.4	3.3		V
				V _{CC} = MIN, V _{IL} = MAX, V _{IH} = MIN	I _{OH} = −24mA	± 10%V _{CC}	2.0			V
						± 5%V _{CC}	2.0			V
V _{OL}	Low-level output voltage			V _{CC} = MIN, V _{IL} = MAX, V _{IH} = MIN	I _{OL} = MAX	± 10%V _{CC}			0.55	V
						± 5%V _{CC}		0.42	0.55	V
V _{IK}	Input clamp voltage			V _{CC} = MIN, I _I = I _{IK}				−0.73	−1.2	V
I _I	Input current at maximum input voltage			V _{CC} = 0.0V, V _I = 7.0V					100	μA
I _{IH}	High-level input current			V _{CC} = MAX, V _I = 2.7V					20	μA
I _{IL}	Low-level input current			V _{CC} = MAX, V _I = 0.5V					−20	μA
I _{OZH}	Off-state output current, High voltage applied			V _{CC} = MAX, V _O = 2.7V					50	μA
I _{OZL}	Off-state output current, Low voltage applied			V _{CC} = MAX, V _O = 0.5V					−50	μA
I _{OS}	Short circuit output current ³			V _{CC} = MAX			−100		−225	mA
I _{CC}	Supply current (total)	74F827	I _{CC} H	V _{CC} = MAX				50	70	mA
			I _{CC} L					70	100	mA
			I _{CC} Z					60	90	mA
		74F828	I _{CC} H	V _{CC} = MAX				30	45	mA
			I _{CC} L					65	85	mA
			I _{CC} Z					55	70	mA

NOTES:

- For conditions shown as MIN or MAX, use the appropriate value specified under operating conditions for the applicable type.
- All typical values are at $V_{CC} = 5\text{V}$, $T_A = 25^\circ\text{C}$.
- Not more than one output should be shorted at one time. For testing I_{OS} , the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a High output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

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AC CHARACTERISTICS

SYMBOL	PARAMETER			LIMITS					UNIT
				T _{amb} = +25°C V _{CC} = 5V C _L = 50pF R _L = 500Ω			T _{amb} = 0 °C to +70°C V _{CC} = 5V ±10% C _L = 50pF R _L = 500Ω		
				Min	Typ	Max	Min	Max	
t _{PLH} t _{PHL}	Propagation delay D _n to Q _n	74F827	Waveform 1	2.0 2.0	5.5 4.5	8.5 8.5	2.0 2.0	9.0 9.0	ns
t _{PZH} t _{PZL}	Output enable time OE _n to Q _n		Waveform 3 Waveform 4	5.0 4.0	8.0 6.0	12.0 10.5	4.5 4.0	14.0 11.5	ns
t _{PHZ} t _{PLZ}	Output disable time OE _n to Q _n		Waveform 3 Waveform 4	2.5 2.5	5.0 5.0	8.0 8.0	2.0 2.0	8.5 8.5	ns
t _{PLH} t _{PHL}	Propagation delay D _n to Q _n	74F828	Waveform 2	2.0 1.0	6.0 3.0	8.5 7.0	2.0 1.0	9.5 8.0	ns
t _{PZH} t _{PZL}	Output enable time OE _n to Q _n		Waveform 3 Waveform 4	6.0 5.0	8.0 7.0	11.5 10.5	5.5 4.5	14.0 12.0	ns
t _{PHZ} t _{PLZ}	Output disable time OE _n to Q _n		Waveform 3 Waveform 4	2.5 1.5	5.0 4.0	8.5 7.0	2.0 1.5	9.0 8.0	ns

AC CHARACTERISTICS

for 1 Output switching with C_L = 300pF and R_L = 500Ω load

SYMBOL	PARAMETER			LIMITS					UNIT
				T _{amb} = +25°C V _{CC} = 5V C _L = 300pF R _L = 500Ω			T _{amb} = 0 °C to +70°C V _{CC} = 5V ±10% C _L = 300pF R _L = 500Ω		
				MIN	Typ	Max	MIN	Max	
t _{PLH} t _{PHL}	Propagation delay D _n to Q _n	74F827	Waveform 1		9.5 7.5	13.0 10.0		14.0 11.0	ns
t _{PZH} t _{PZL}	Output enable time OE _n to Q _n		Waveform 3 Waveform 4		15.0 9.5	20.0 13.0		21.0 14.0	ns
t _{PHZ} t _{PLZ}	Output disable time OE _n to Q _n		Waveform 3 Waveform 4		15.0 9.5	19.0 13.5		20.0 14.0	ns
t _{PLH} t _{PHL}	Propagation delay D _n to Q _n	74F828	Waveform 2		10.0 6.0	13.0 9.0		14.0 10.0	ns
t _{PZH} t _{PZL}	Output enable time OE _n to Q _n		Waveform 3 Waveform 4		15.5 10.5	19.0 13.0		21.0 14.0	ns
t _{PHZ} t _{PLZ}	Output disable time OE _n to Q _n		Waveform 3 Waveform 4		15.0 10.0	18.0 13.0		20.0 14.5	ns

Buffers

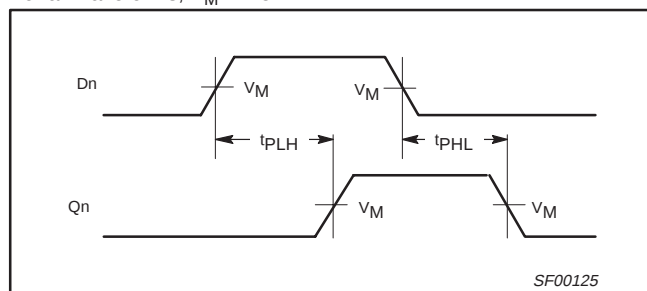
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AC CHARACTERISTICS

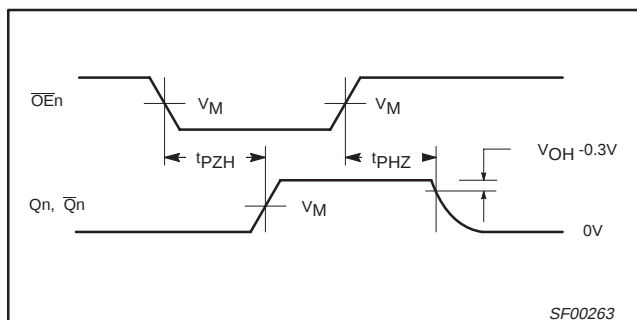
for 10 Outputs switching with $C_L = 300\text{pF}$ and $R_L = 500\Omega$ load

SYMBOL	PARAMETER			LIMITS					UNIT
				$T_{\text{amb}} = +25^{\circ}\text{C}$ $V_{\text{CC}} = 5\text{V}$ $C_{\text{L}} = 50\text{pF}$ $R_{\text{L}} = 500\Omega$			$T_{\text{amb}} = 0^{\circ}\text{C to } +70^{\circ}\text{C}$ $V_{\text{CC}} = 5\text{V} \pm 10\%$ $C_{\text{L}} = 50\text{pF}$ $R_{\text{L}} = 500\Omega$		
MIN	Typ	Max	MIN	Max					
t_{PLH} t_{PHL}	Propagation delay D_{n} to Q_{n}	74F827	Waveform 1		12.0 14.0	16.0 17.0		17.0 18.0	ns
t_{PZH} t_{PZL}	Output enable time $\overline{\text{OE}}_{\text{n}}$ to Q_{n}		Waveform 3 Waveform 4		15.0 17.0	20.0 21.0		21.0 21.5	ns
t_{PHZ} t_{PLZ}	Output disable time $\overline{\text{OE}}_{\text{n}}$ to Q_{n}		Waveform 3 Waveform 4		15.0 12.5	19.0 15.5		20.0 16.0	ns
t_{PLH} t_{PHL}	Propagation delay D_{n} to $\overline{Q}_{\text{n}}$	74F828	Waveform 2		10.0 10.0	17.0 13.5		18.0 14.0	ns
t_{PZH} t_{PZL}	Output enable time $\overline{\text{OE}}_{\text{n}}$ to $\overline{Q}_{\text{n}}$		Waveform 3 Waveform 4		18.0 15.0	21.0 18.0		23.0 19.0	ns
t_{PHZ} t_{PLZ}	Output disable time $\overline{\text{OE}}_{\text{n}}$ to $\overline{Q}_{\text{n}}$		Waveform 3 Waveform 4		16.5 11.5	19.5 14.5		22.5 15.0	ns

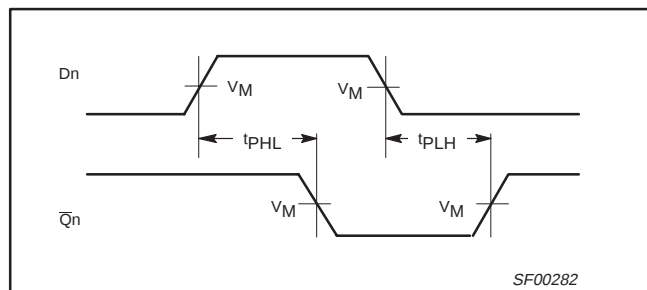
AC WAVEFORMS

For all waveforms, $V_M = 1.5\text{V}$ 

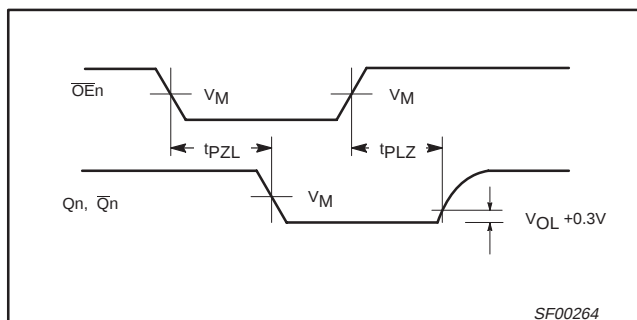
Waveform 1. Propagation Delay for Non-Inverting Output



Waveform 3. 3-State Output Enable Time to High Level and Output Disable Time from High Level



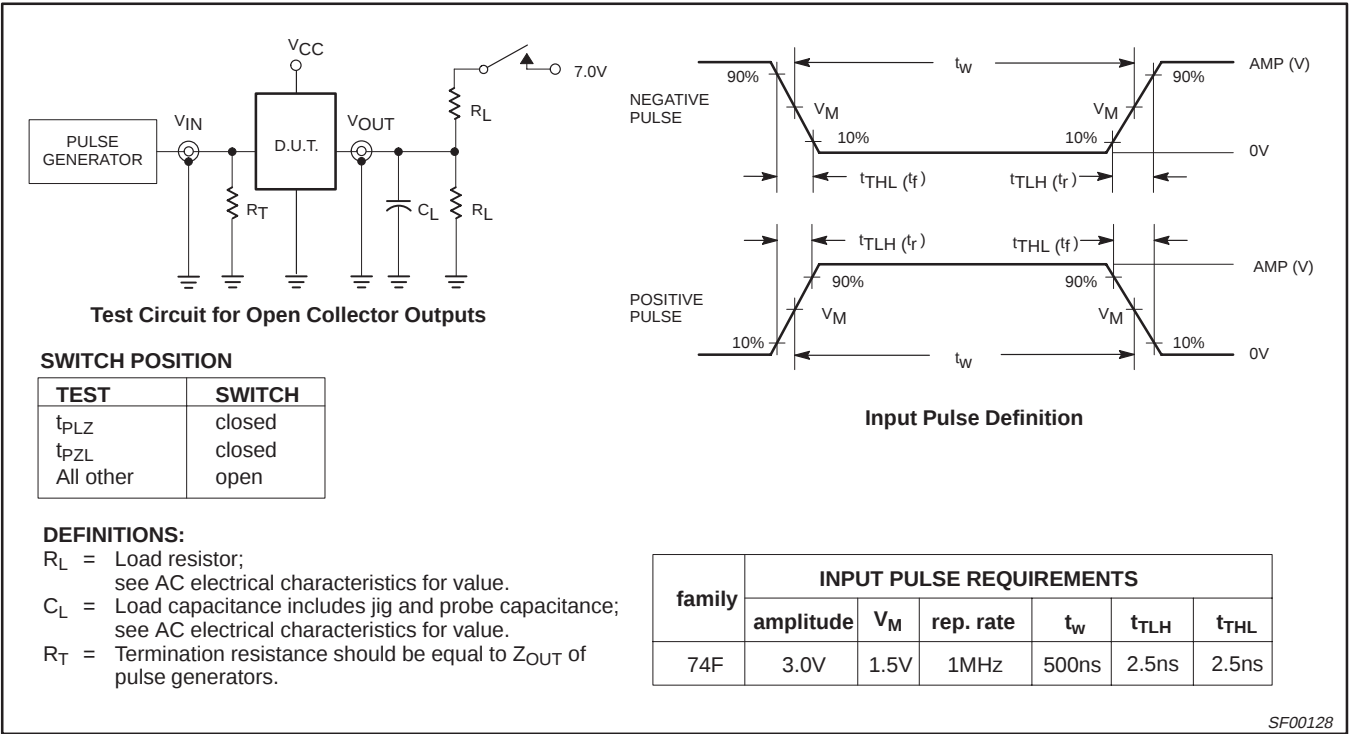
Waveform 2. Propagation Delay for Inverting Output



Waveform 4. 3-State Output Enable Time to Low Level and Output Disable Time from Low Level

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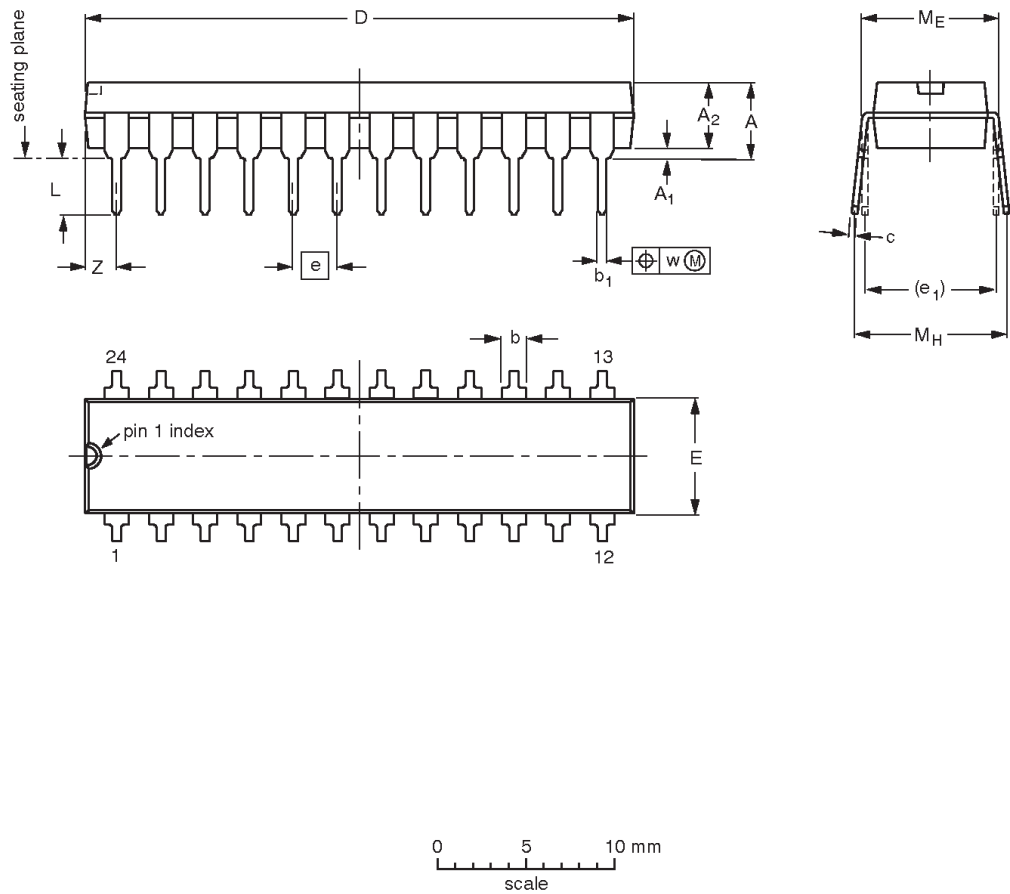


Buffers

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DIP24: plastic dual in-line package; 24 leads (300 mil)

SOT222-1



DIMENSIONS (millimetre dimensions are derived from the original inch dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	c	D ⁽¹⁾	E ⁽¹⁾	e	e ₁	L	M _E	M _H	w	Z ⁽¹⁾ max.
mm	4.70	0.38	3.94	1.63 1.14	0.56 0.43	0.36 0.25	31.9 31.5	6.73 6.48	2.54	7.62	3.51 3.05	8.13 7.62	10.03 7.62	0.25	2.05
inches	0.185	0.015	0.155	0.064 0.045	0.022 0.017	0.014 0.010	1.256 1.240	0.265 0.255	0.100	0.300	0.138 0.120	0.32 0.30	0.395 0.300	0.01	0.081

Note
1. Plastic or metal protrusions of 0.01 inches maximum per side are not included.

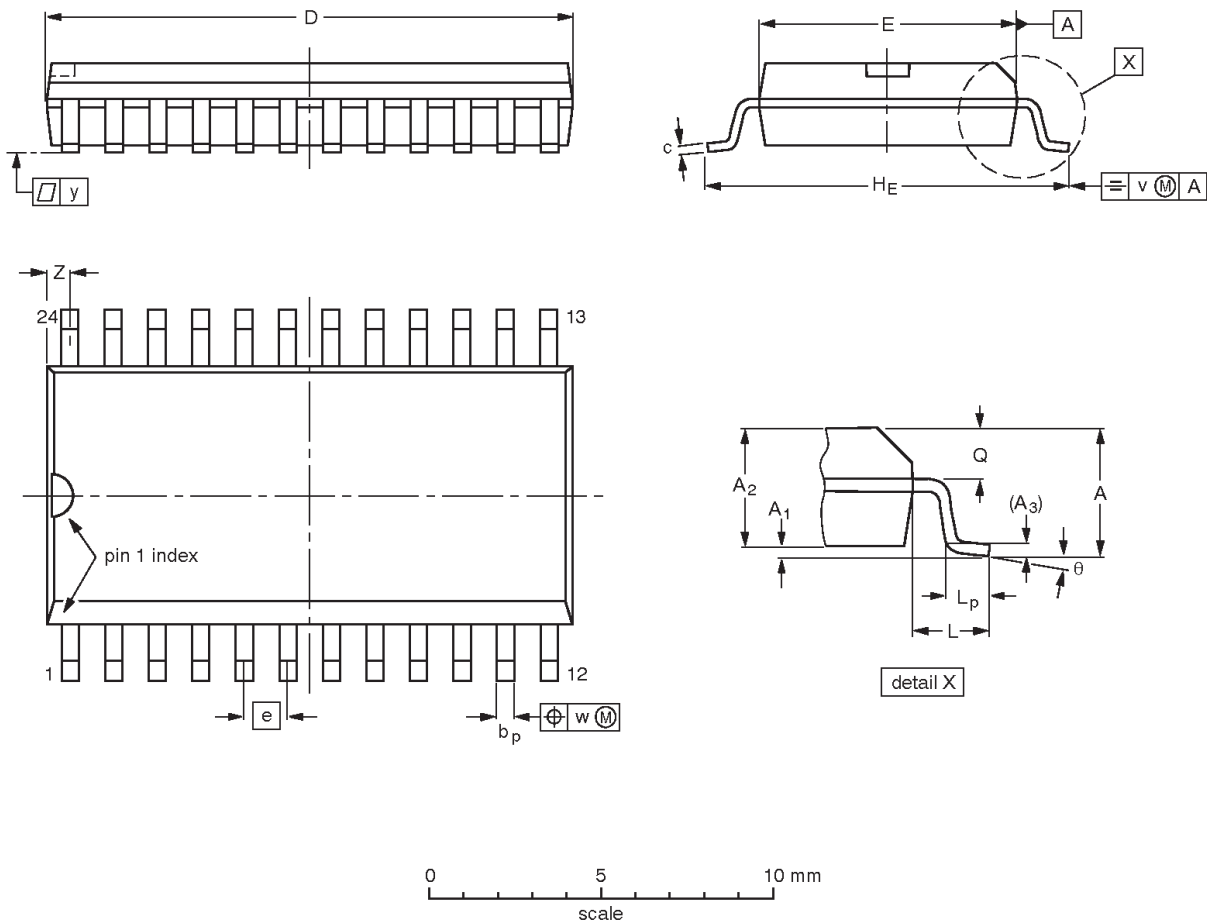
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT222-1		MS-001AF				95-03-11

Buffers

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SO24: plastic small outline package; 24 leads; body width 7.5 mm

SOT137-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	15.6 15.2	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8° 0°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.61 0.60	0.30 0.29	0.050	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

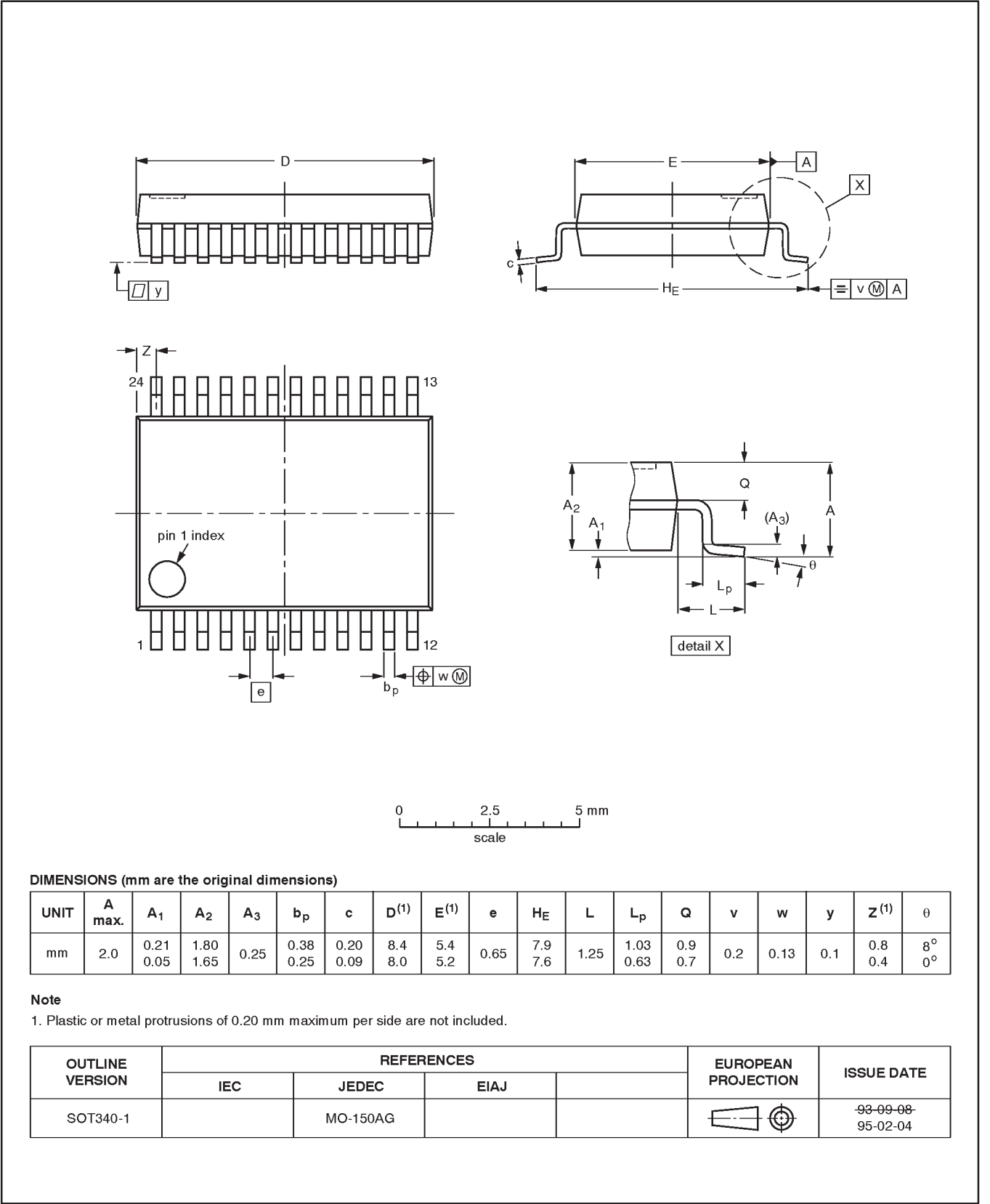
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT137-1	075E05	MS-013AD				-95-01-24 97-05-22

Buffers

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SSOP24: plastic shrink small outline package; 24 leads; body width 5.3 mm

SOT340-1



Buffers

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DEFINITIONS		
Data Sheet Identification	Product Status	Definition
Objective Specification	Formative or in Design	This data sheet contains the design target or goal specifications for product development. Specifications may change in any manner without notice.
Preliminary Specification	Preproduction Product	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.
Product Specification	Full Production	This data sheet contains Final Specifications. Philips Semiconductors reserves the right to make changes at any time without notice, in order to improve design and supply the best possible product.

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